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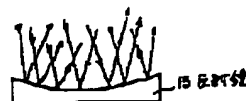
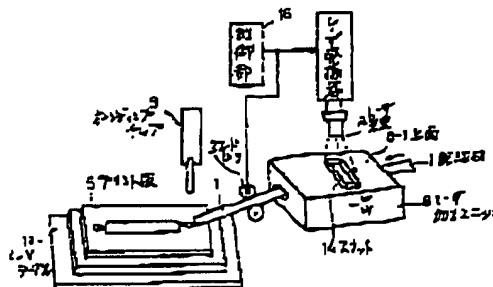
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TITLE : WIRE BONDER



**ABSTRACT :** **PURPOSE:** To remove coating of a polyurethane coated wire at a specified position accurately only as long as a fixed length over the whole circumference by reflecting laser beams to the inside of the underside of a laser beam machining unit and installing a reflecting mirror regulating irradiation on the underside section of a wiring material and the range of irradiation.

**CONSTITUTION:** The width  $W$  of a slit 14 in a laser beam machining unit 8 regulates irradiation width to a polyurethane coated wire 1 of laser beams A. The length (l) of the removal of the coating of an top face section in the polyurethane coated wire 1 is specified by the width  $W$ , and arbitrary length (l) is acquired with high accuracy by adjusting width  $W$ . Laser beams passing through both end sections of the slit 14 are reflected by a reflecting mirror 15, and apply the underside section of the urethane coated wire 1 and coating is gotten rid of. The angle of reflection of the reflecting mirror is adjusted by the thickness of the wire and a distance, etc., with the wire, coating is taken off at the same position as the top face while the length of the removal of coating is brought to (l), and the polyurethane coated wire 1 is removed in specified length (l) extending over the whole circumference. A control section 16 controls a feed roller 3 so that the position of the removal of coating in the polyurethane coated wire 1 is stopped at the position of the slit 14.

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